

NP284 Series (Open Top)

Chip Scale Package (CSP, 0.50mm Pitch)

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	30mΩ max. at 10mA/20mV max.
Operating Temperature Range:	-40°C to +150°C
Contact Force:	11gf per pin approx.
Grid Size:	35 x 35
Pin Count:	264 pins

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
Polyethersulphone (PES), glass-filled

Contacts: Beryllium Copper (BeCu)

Plating: Gold over Nickel

Features

- Open top type socket for CSP packages with 0.50mm pitch
- Self contacting structure without upper pressing force (ZIF)
- Fan-out Terminal type, designed to reduce ball damage

Part Number (Details)

NP284 - 264 09 *

Series No.

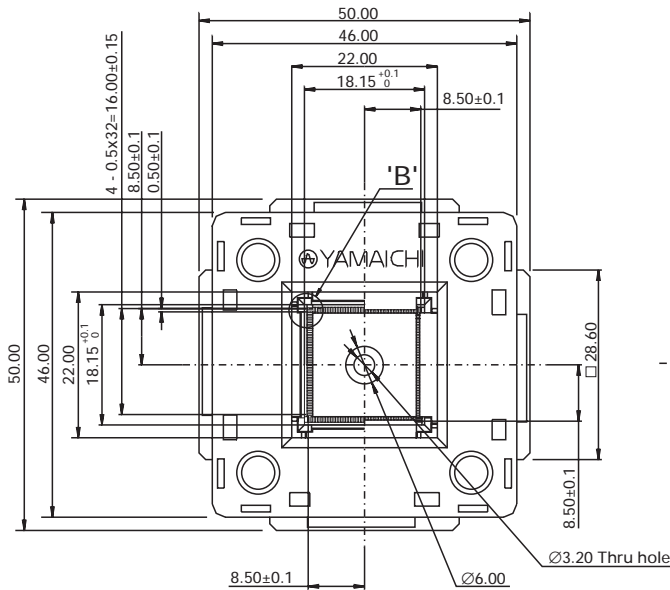
No. of Contact Pins

Design Number

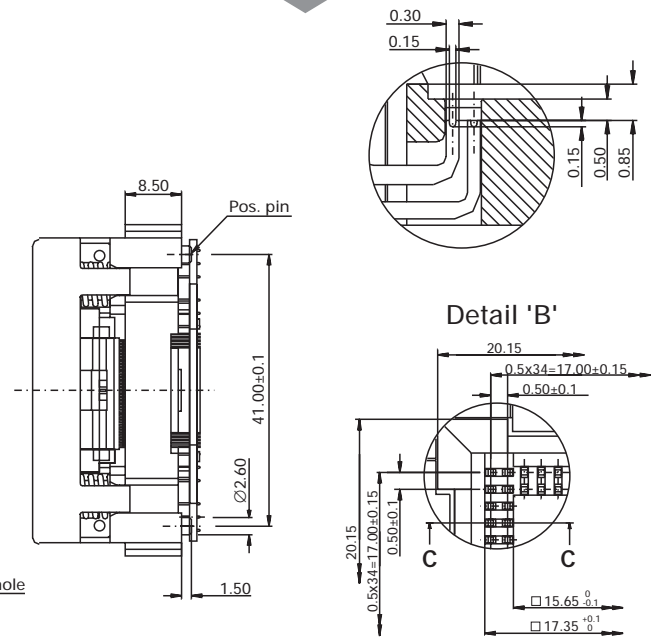
Positioning Pin: N = Without
P = With

Applicable Dimensions (Reference Only)

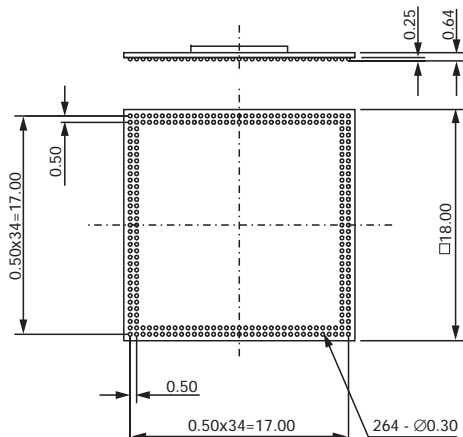
Outline Socket Dimensions



Contact Details (Section C - C)



Matching IC Dimensions



Recommended PC Board Layout

